



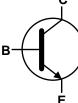
**DSS2540M** 

#### 40V NPN LOW V<sub>CE(sat)</sub> TRANSISTOR

#### Features

- BV<sub>CEO</sub> > 40V
- I<sub>C</sub> = 500mA High Collector Current
- I<sub>CM</sub> = 1A Peak Pulse Current
- P<sub>D</sub> = 1000mW Power Dissipation
- Low Collector-Emitter Saturation Voltage, V<sub>CE(sat)</sub>
- 0.60mm<sup>2</sup> Package Footprint, 13 times Smaller than SOT23
- 0.5mm Height Package Minimizing Off-Board Profile
- Complementary NPN Type DSS3540M
- Totally Lead Free & Fully RoHS Compliant (Notes 1 & 2)
- Halogen and Antimony Free. "Green" Device (Note 3)
- Qualified to AEC-Q101 Standards for High Reliability

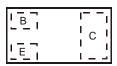




Device Symbol

Mechanical Data

- Case: X1-DFN1006-3
- Case Material: Molded Plastic, "Green" Molding Compound. UL Flammability Classification Rating 94V-0
- Moisture Sensitivity: Level 1 per J-STD-020
  Terminals: Finish NiPdAu.
- Solderable per MIL-STD-202, Method 208 @
- Weight: 0.0009 grams (Approximate)



Top View Device Schematic

## Ordering Information (Note 4)

Product	Marking	Reel size (inches)	Tape width (mm)	Quantity per reel
DSS2540M-7	TC	7	8mm	3,000
DSS2540M-7B	TC	7	8mm	10,000

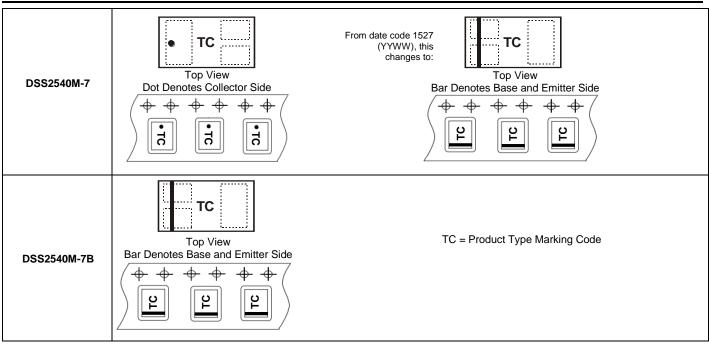
Notes: 1. No purposely added lead. Fully EU Directive 2002/95/EC (RoHS) & 2011/65/EU (RoHS 2) compliant.

2. See http://www.diodes.com/quality/lead\_free.html for more information about Diodes Incorporated's definitions of Halogen- and Antimony-free, "Green" and Lead-free.

3. Halogen- and Antimony-free "Green" products are defined as those which contain <900ppm bromine, <900ppm chlorine (<1500ppm total Br + Cl) and <1000ppm antimony compounds.

4. For packaging details, go to our website at http://www.diodes.com.

## Marking Information





# Absolute Maximum Ratings (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit
Collector-Base Voltage	V <sub>CBO</sub>	40	V
Collector-Emitter Voltage	V <sub>CEO</sub>	40	V
Emitter-Base Voltage	V <sub>EBO</sub>	6	V
Collector Current - Continuous	Ic	500	mA
Peak Pulse Collector Current	I <sub>CM</sub>	1	А
Peak Base Current	I <sub>BM</sub>	100	mA

## Thermal Characteristics (@T<sub>A</sub> = +25°C, unless otherwise specified.)

Characteristic	Symbol	Value	Unit		
Power Dissipation	(Note 5)	D	400	mW	
	(Note 6)	P <sub>D</sub>	1000		
Thermal Resistance, Junction to Ambient	(Note 5)	6	310	°C/W	
Thermal Resistance, Junction to Ambient	(Note 6)	R <sub>0JA</sub>	120		
Thermal Resistance, Junction to Lead (Note 7)		R <sub>θJL</sub>	120	°C/W	
Operating and Storage and Temperature Ran	T <sub>J</sub> , T <sub>STG</sub>	-55 to +150	°C		

### ESD Ratings (Note 8)

Characteristic	Symbol	Value	Unit	JEDEC Class
Electrostatic Discharge - Human Body Model	ESD HBM	4,000	V	3A
Electrostatic Discharge - Machine Model	ESD MM	400	V	В

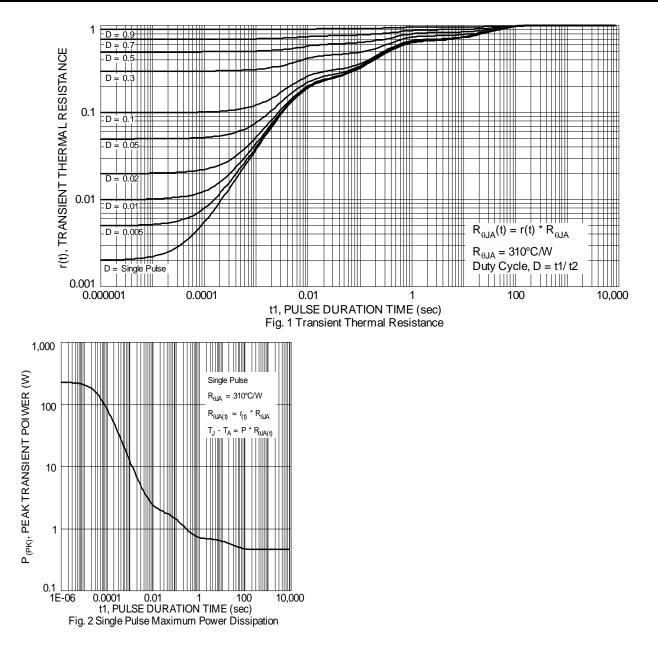
5. For the device mounted on minimum recommended pad layout 1oz copper that is on a single-sided 1.6mm FR4 PCB; device is measured under still air conditions whilst operating in steady state condition. The entire exposed collector pad is attached to the heatsink. Notes:

6. Same as Note 5, except the exposed collector pad is mounted on 25mm x 25mm 2oz copper.

Thermal resistance from junction to solder-point (on the exposed collector pad).
 Refer to JEDEC specification JESD22-A114 and JESD22-A115.



## **Thermal Characteristics**





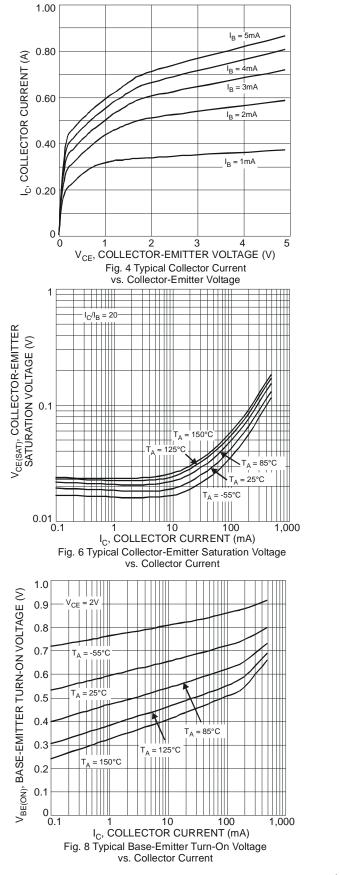
## **Electrical Characteristics** (@T<sub>A</sub> = +25°C, unless otherwise specified.)

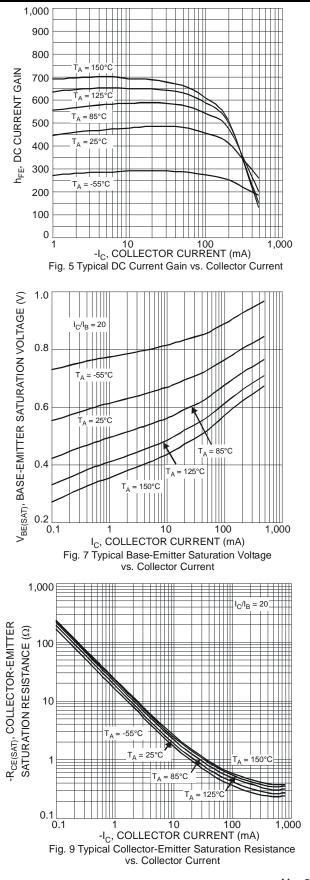
Characteristic	Symbol	Min	Тур	Max	Unit	Test Condition
OFF CHARACTERISTICS						•
Collector-Base Breakdown Voltage	BV <sub>CBO</sub>	40	_	_	V	$I_{\rm C} = 100 \mu {\rm A}, I_{\rm E} = 0$
Collector-Emitter Breakdown Voltage (Note 9)	BV <sub>CEO</sub>	40		_	V	$I_{\rm C} = 10 {\rm mA}, I_{\rm B} = 0$
Emitter-Base Breakdown Voltage	BV <sub>EBO</sub>	6		_	V	$I_{E} = 100 \mu A, I_{C} = 0$
Collector Cutoff Current				100	nA	$V_{CB} = 30V, I_E = 0$
	I <sub>CBO</sub>		_	50	μA	$V_{CB} = 30V, I_E = 0, T_A = +150^{\circ}C$
Emitter Cutoff Current	I <sub>EBO</sub>	_	_	100	nA	$V_{EB} = 5V, I_{C} = 0$
ON CHARACTERISTICS (Note 9)						
		200	_			$V_{CE} = 2V, I_{C} = 10mA$
DC Current Gain	h <sub>FE</sub>	150		—	—	$V_{CE} = 2V, I_{C} = 100mA$
		50		—		$V_{CE} = 2V, I_{C} = 500mA$
				50	mV	$I_{C} = 10 \text{mA}, I_{B} = 0.5 \text{mA}$
Collector-Emitter Saturation Voltage				100		$I_{C} = 100 \text{mA}, I_{B} = 5 \text{mA}$
Collector-Emiller Saturation voltage	V <sub>CE(sat)</sub>			200	IIIV	$I_{C} = 200 \text{mA}, I_{B} = 10 \text{mA}$
		—		250		$I_{\rm C} = 500 {\rm mA}, I_{\rm B} = 50 {\rm mA}$
Collector-Emitter Saturation Resistance	R <sub>CE(sat)</sub>	_	_	500	mΩ	$I_{C} = 500 \text{mA}, I_{B} = 50 \text{mA}$
Base-Emitter Saturation Voltage	V <sub>BE(sat)</sub>	_		1.2	V	$I_{\rm C} = 500 {\rm mA}, I_{\rm B} = 50 {\rm mA}$
Base-Emitter Turn On Voltage	V <sub>BE(on)</sub>			1.1	V	$V_{CE} = 2V, I_{C} = 100 \text{mA}$
SMALL SIGNAL CHARACTERISTICS						
Output Capacitance	C <sub>obo</sub>			6	pF	V <sub>CB</sub> = 10V, f = 1.0MHz
Current Gain-Bandwidth Product	f⊤	250	300	_	MHz	V <sub>CE</sub> = 5V, I <sub>C</sub> = 100mA, f = 100MHz

Note: 9. Measured under pulsed conditions. Pulse width  $\leq$  300µs. Duty cycle  $\leq$  2%.



### Typical Electrical Characteristics (@TA = +25°C, unless otherwise specified.)



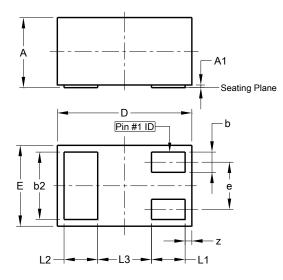


DSS2540M Document number: DS31820 Rev. 4 - 2 Downloaded from Arrow.com.



## **Package Outline Dimensions**

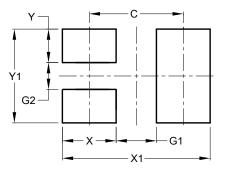
Please see AP02002 at http://www.diodes.com/datasheets/ap02002.pdf for the latest version.



Х	X1-DFN1006-3					
Dim	Min	Max	Тур			
Α	0.47	0.53	0.50			
A1	0.00	0.05	0.03			
b	0.10	0.20	0.15			
b2	0.45	0.55	0.50			
D	0.95	1.075	1.00			
E	0.55	0.675	0.60			
е	1	-	0.35			
L1	0.20	0.30	0.25			
L2	0.20	0.30	0.25			
L3	-	-	0.40			
z	0.02	0.08	0.05			
All D	All Dimensions in mm					

# Suggested Pad Layout

Please see AP02001 at http://www.diodes.com/datasheets/ap02001.pdf for the latest version.



Dimensions	Value (in mm)
С	0.70
G1	0.30
G2	0.20
Х	0.40
X1	1.10
Y	0.25
Y1	0.70



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